

Abstract

5 **Method and apparatus for removing an edge region of a layer applied to a
 substrate and for coating a substrate and a substrate**

10 The invention relates to a method and an apparatus for removing an edge region of a
layer applied to a substrate and for coating a substrate, in particular, with a photoresist
layer. Furthermore, the present invention relates to a substrate, onto which a layer, in
particular, a photoresist layer for use in a microlithographic process, is applied,
wherein an edge region of the layer is removed according to the invention.

15 In the method, a laser beam is imaged onto the edge region, and the edge region is
removed by the laser beam. In this manner, the edge region can be removed reliably
and precisely, without damage to or contamination of regions of the layer which are
not to be removed.